



SOT2112-1

HVQFN114, thermal enhanced very thin quad flat package, no leads, 114 terminals, 0.5 mm pitch, 10 mm x 10 mm x 0.85 mm body

11 June 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN114
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	08-04-2020
Manufacturer package code	98ASA01586D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.9	10	10.1	mm
package width	9.9	10	10.1	mm
seated height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	114	-	



HVQFN114, thermal enhanced very thin quad flat package, no leads, 114 terminals, 0.5 mm pitch, 10 mm x 10 mm x 0.85 mm body

2 Package outline

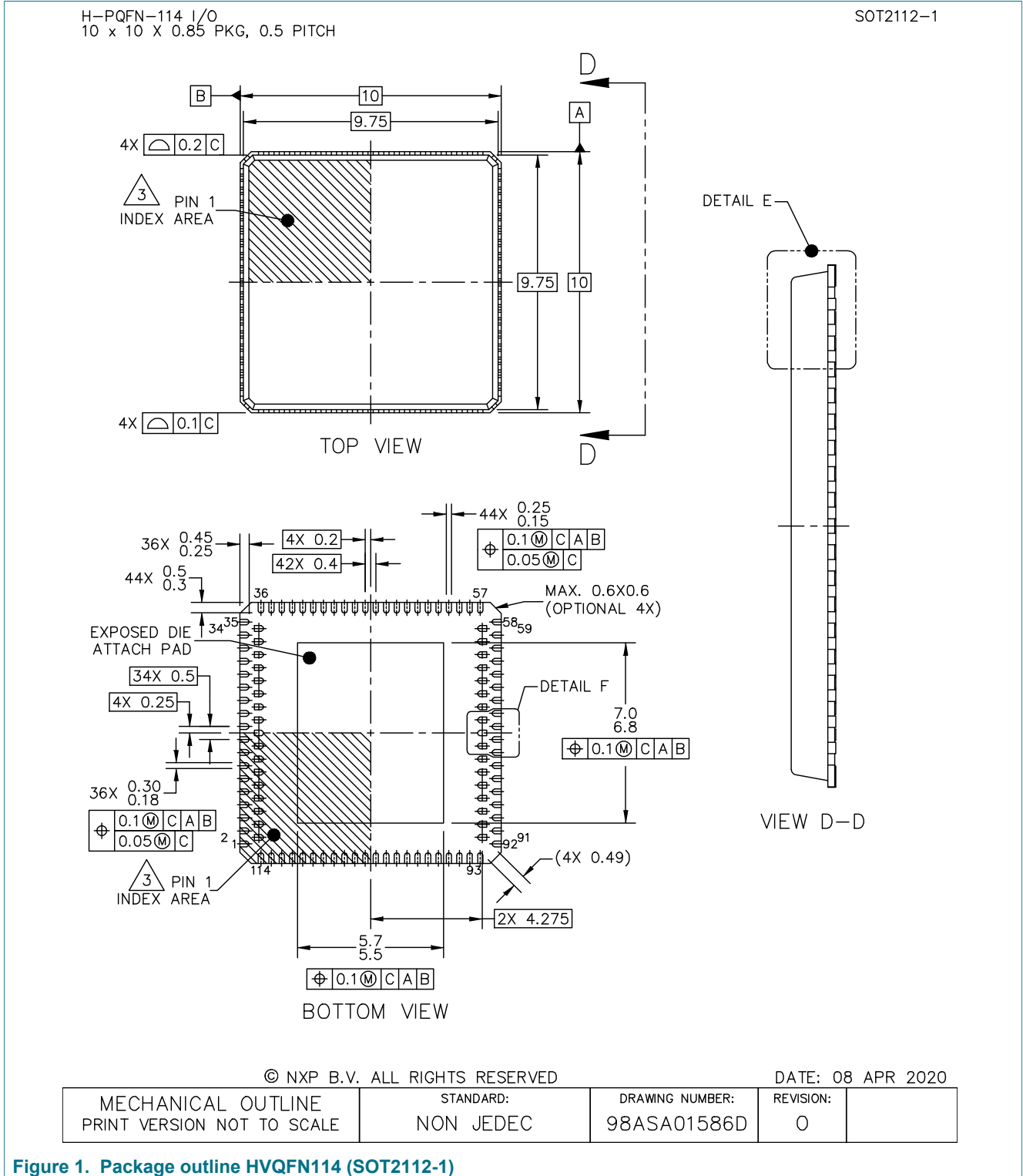
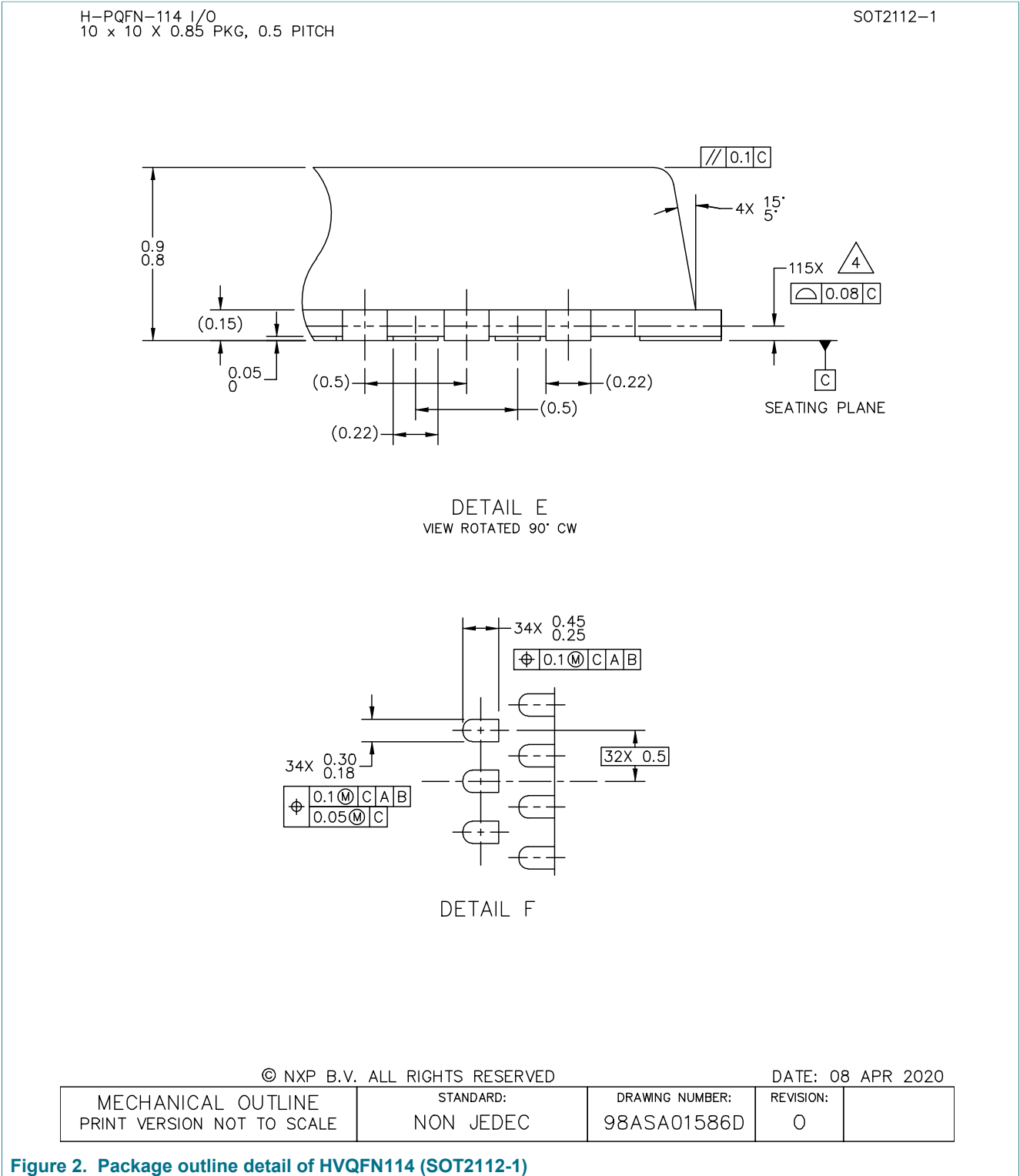


Figure 1. Package outline HVQFN114 (SOT2112-1)

HVQFN114, thermal enhanced very thin quad flat package, no leads, 114 terminals, 0.5 mm pitch, 10 mm x 10 mm x 0.85 mm body



3 Soldering

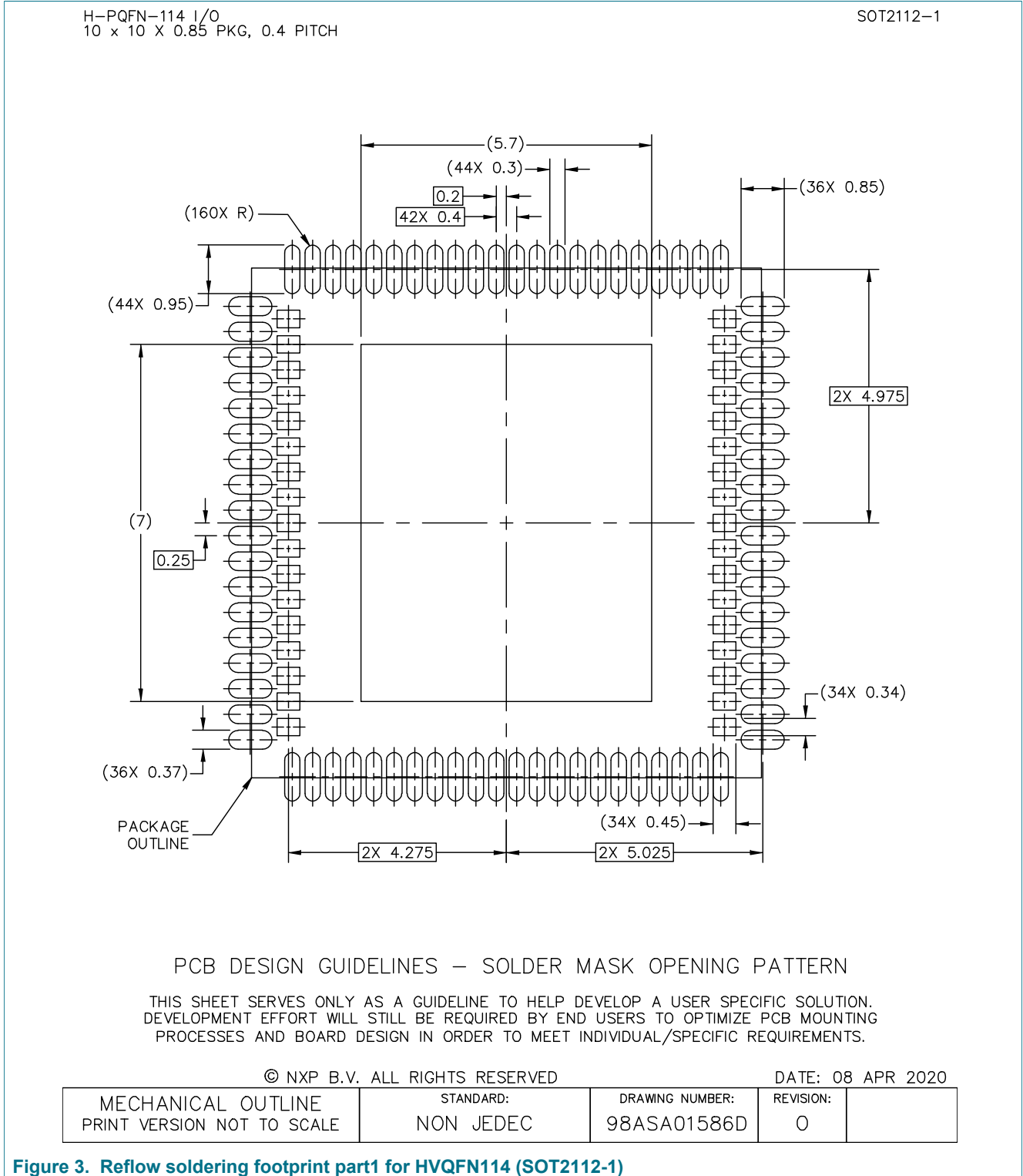
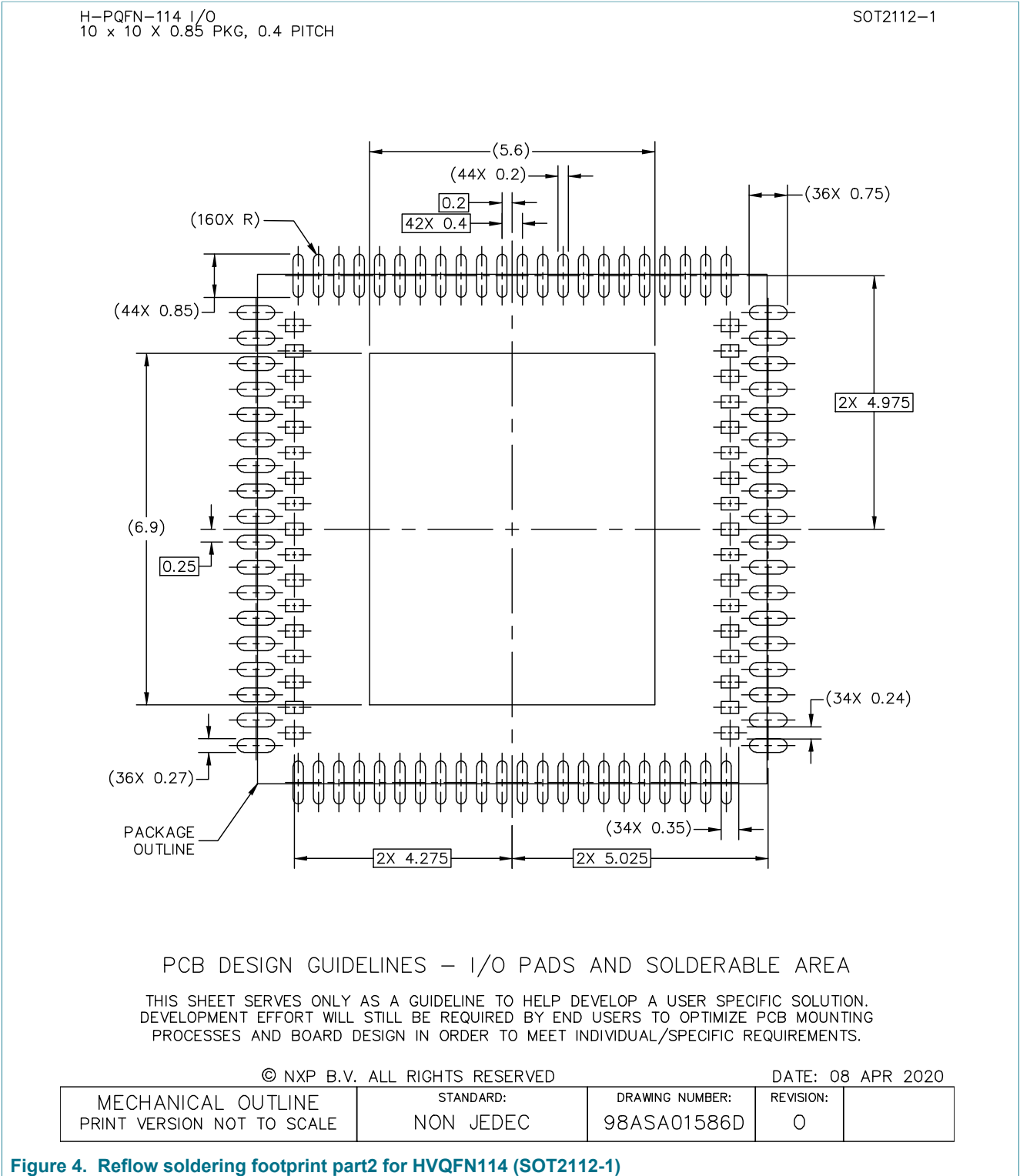


Figure 3. Reflow soldering footprint part1 for HVQFN114 (SOT2112-1)

HVQFN114, thermal enhanced very thin quad flat package, no leads, 114 terminals, 0.5 mm pitch, 10 mm x 10 mm x 0.85 mm body



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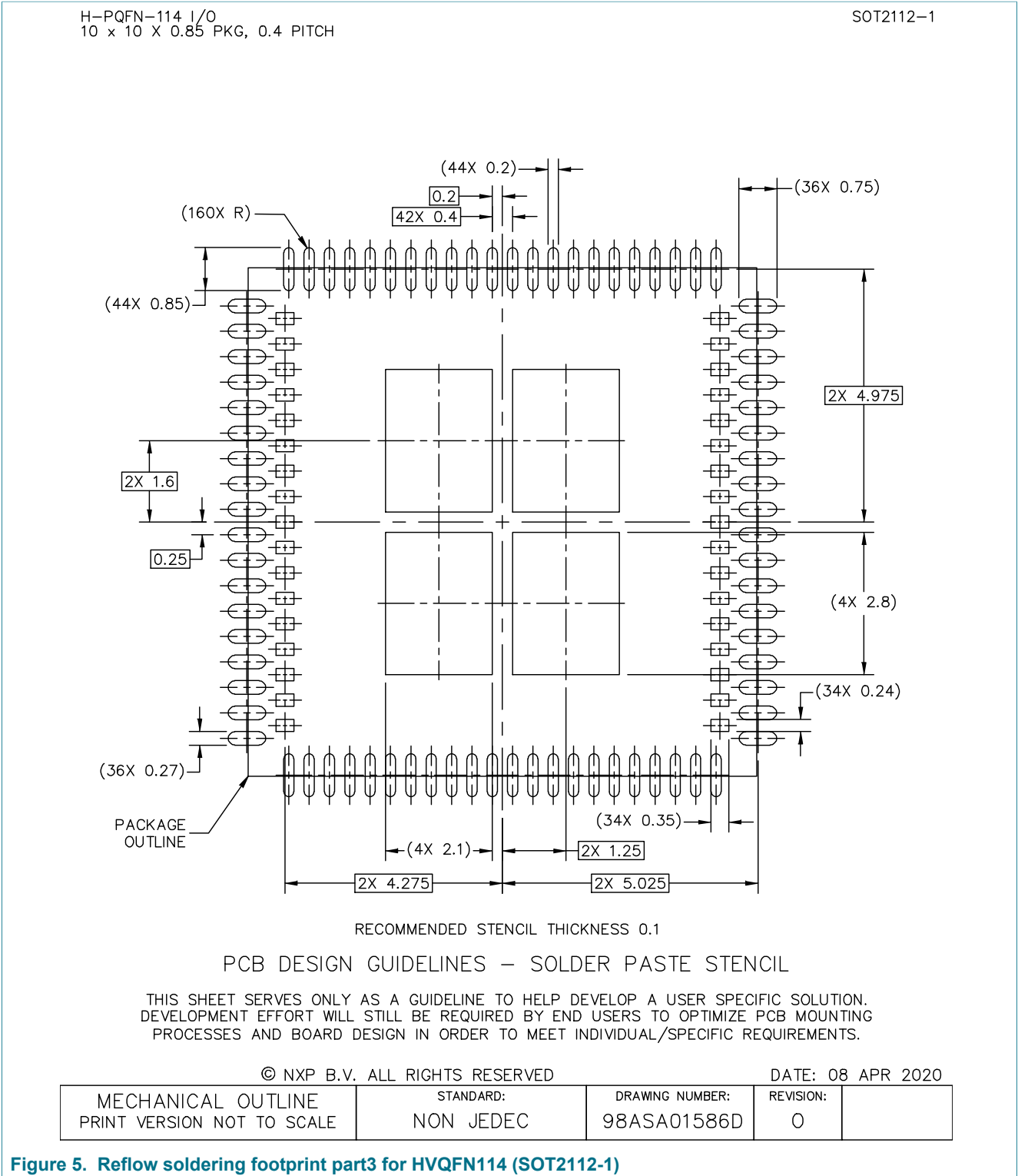


Figure 5. Reflow soldering footprint part3 for HVQFN114 (SOT2112-1)

HVQFN114, thermal enhanced very thin quad flat package, no leads, 114 terminals, 0.5 mm pitch, 10 mm x 10 mm x 0.85 mm body

H-PQFN-114 I/O
10 x 10 X 0.85 PKG, 0.4 PITCH

SOT2112-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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DATE: 08 APR 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01586D	REVISION: 0	
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Figure 6. Package outline note HVQFN114 (SOT2112-1)

4 Legal information

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